

Permanent Wafer Bonding at Room Temperature

Atomic Diffusion Bonding

Any Substrates Available

Various Bonding Materials

Ambient Control Sealing

● Substrates



Si - Synthetic quartz

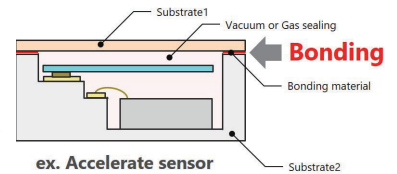


Synthetic quartz - Synthetic quartz

● Chip sealing



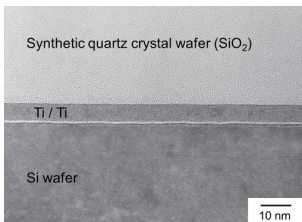
Patterned Silicon - Quartz



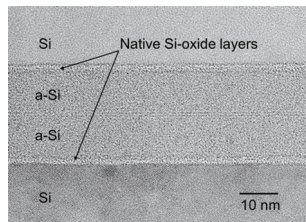
Silicon, Compound, Quartz, Glass or Others

● Bonding material examples

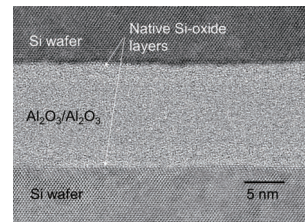
Titanium*



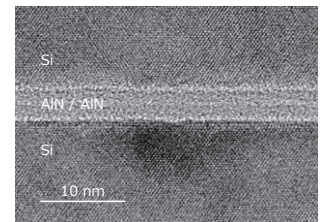
Silicon*



Aluminum Oxide*



Aluminum Nitride



* Courtesy of Shimatsu Laboratory, Tohoku University

BC7000 for $\phi 100 / \phi 150$ mm



BC7300 for $\phi 200 / \phi 300$ mm



Coming Soon !

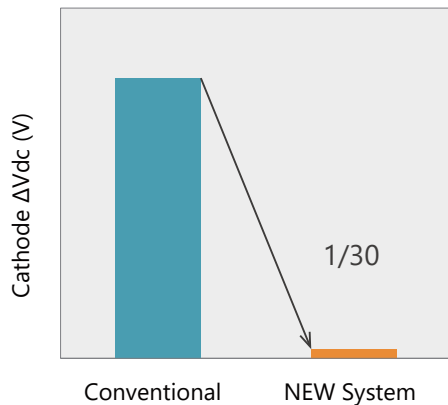
Dielectric Film Sputtering

Unique RF Plasma Technology

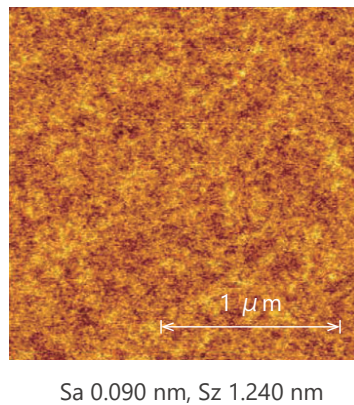
Excellent
Stability

Smooth
Surface

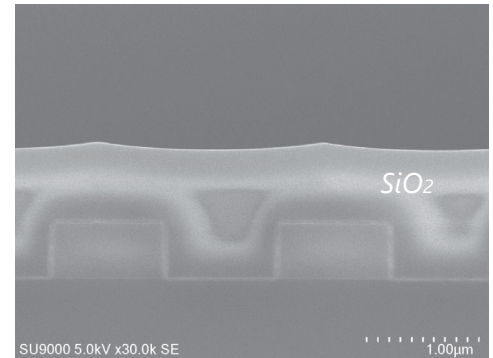
Seamless
Filling



Excellent Vdc stability with process running



Extreme smooth surface morphology by SiO₂



Seamless & void less by SiO₂ filling

EB2500 for R&D



EC7430 for Volume production

